



PATENT
Customer No. 22,852
Attorney Docket No. 04329.2553

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Masaki HATANO, et al.

Serial No.: 09/816,177

Filed: March 26, 2001

For: SEMICONDUCTOR DEVICE

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Group Art Unit: 2822

Examiner: Mitchell, James M.

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

AMENDMENT

In reply to the Office Action dated December 26, 2001, with a period for response extending through April 26, 2002, by the attached Petition for Extension of Time of One Month and requisite fee payment, please amend the application as follows:

IN THE CLAIMS:

Please cancel claims 3 – 12 without prejudice or disclaimer of the subject matter therein, amend claim 1, and add new claims 13 – 22 as follows:

1. (Amended) A semiconductor device comprising:

a Cu film provided above a main surface of a semiconductor substrate and used as a

wiring;

an intermediate layer formed at least on the Cu film, the intermediate layer comprising a

TaN film formed on the Cu film and a Ta film formed on the TaN film; and

an Al film formed on the Ta film and used as a pad.

FINNEGAN
HENDERSON
FARABOW
GARRETT &
DUNNER LLP

1300 I Street, NW
Washington, DC 20005
202.408.4000
Fax 202.408.4400
www.finnegan.com